Metal Oxide Semiconductor Enhancement Mode Transistor

Last updated 12/22/23



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- Planer Structure
 - W width breadth of region for carriers to transit from Source to Drain
 - L length distance a carrier must travel to transit from Source to Drain



- Planer N-MOS Operation
 - Large Positive Gate Bias
 - Depletion region is formed
 - Mobile holes pushed away (region is depleted of holes)
 - Net negative (fixed) charge left behind
 - Electrons are drawn from the Si to form an inversion layer



A channel is formed from Source to Drain Electrons can flow through this channel Body tied to 'gnd' to ensure the S/D diodes are reverse biased

- Planer N-MOS Operation
 - Large Positive Gate Bias + Positive Bias from Drain to Source
 - Electrons move from Source to Drain
 - Current flows from Drain to Source



Body tied to 'gnd' to ensure the S/D diodes are reverse biased

- Planer P-MOS Operation
 - Large Negative Gate Bias
 - Depletion region is formed
 - Mobile electrons pushed away (region is depleted of electrons)
 - Net positive (fixed) charge left behind
 - Holes are drawn from the Si to form an inversion layer



A channel is formed from Source to Drain Holes can flow through this channel Body tied to 'Vdd' to ensure the S/D diodes are reverse biased

- Planer P-MOS Operation
 - Large Negative Gate Bias + Positive Bias from Source to Drain
 - Holes move from Source to Drain
 - Current flows from Source to Drain



- Planer Enhancement Mode Transistors
 - A bias is required to form the channel
 - 4-terminal symbol



N-channel



N-ch	nannel
G	
	S

Note – almost all N-MOS and P-MOS devices used today are enhancement mode – so the dashed line is omitted

• In digital applications the Body is typically tied to

P-channel

- Vdd for P-MOS
- Gnd for N-MOS
- 3-terminal symbol
- Simplified logic symbols

- Planer Enhancement Mode Transistor Parameters
 - W width of the transistor
 - L length of the transistor (S to D)
 - V_{th} threshold voltage (inversion layer formed)
 - Kn, Kp conduction parameter

$$K_n = \frac{W\mu_n C_{ox}}{2L} \qquad \qquad K_p = \frac{W\mu_p C_{ox}}{2L}$$

$$K_n = \frac{k'_n W}{2 L} \qquad \qquad K_p = \frac{k'_p W}{2 L}$$
$$k'_n = \mu_n C_{ox} \qquad \qquad k'_p = \mu_p C_{ox}$$

 $\mu_n \sim 3 \ge \mu_p$, C_{ox} fixed for a given semiconductor process

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